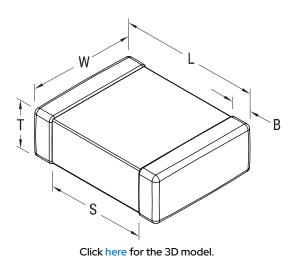


C1812X511J2TACTU

Aliases (C1812X511J2TAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 510 pF, 5%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



General Information		
Series	SMD Comm X8G HT150C Flex	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Flexible Termination	
Marking	No	
AEC-Q200	No	
Typical Component Weight	67 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions	
Chip Size	1812
L	4.5mm +/-0.4mm
W	3.2mm +/-0.3mm
Т	1mm +/-0.10mm
S	2.3mm MIN
В	0.7mm +/-0.35mm

Т	1mm +/-0.10mm	
S	2.3mm MIN	
В	0.7mm +/-0.35mm	
Packaging Specifications		
Packaging	T&R, 180mm, Plastic Tape	

Specifications	
Capacitance	510 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	5%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

1000	Dissipation Factor	0.1% 1 MHz 1.0\
	·	
	Aging Rate	0% Loss/Deca Time is 1000 H
	Insulation Resistance	100 GOhms
	1000	Dissipation Factor Aging Rate

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